

### Description

The CLAMP0524P is an ultra low capacitance TVS array,utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. The CLAMP0524P has an ultra-low capacitance with a typical value at 0.3pF, and complies with the IEC 61000-4-2 (ESD) standard with  $\pm 25\text{kV}$  air and  $\pm 20\text{kV}$  contact discharge. It is assembled into a 10-pin 2.5x1.0x0.5mm lead-free DFN package. The flow through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance between high speed differential lines such as USB 3.0 and HDMI. The small size, ultra-low capacitance and high ESD surge protection make CLAMP0524P an ideal choice to protect HDMI, MDDI, USB3.0 and other high speed ports.

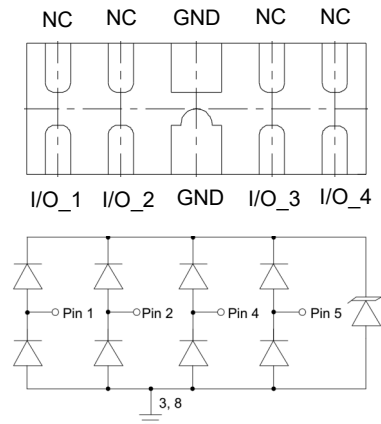
### Features

- Ultra low capacitance: 0.3pF typical (I/O to I/O)
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Up to 4 lines protects
- Leadless flow-through package
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 25\text{kV}$
    - Contact discharge:  $\pm 20\text{kV}$
  - IEC61000-4-5 (Lightning) 5A (8/20 $\mu\text{s}$ )
- RoHS Compliant

### Ordering Information

Part Number	Packaging	Reel Size
CLAMP0524P	3000/Tape & Reel	7 inch

### Dimensions and Pin Configuration



Circuit and Pin Schematic

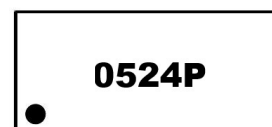
### Mechanical Characteristics

- Package: DFN2510-10L (2.5×1.0×0.5mm)
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound.
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

### Applications

- HDMI 1.3 & 1.4, USB 2.0 & 3.0 and MDDI ports
- Monitors and flat panel displays
- Set-top box and Digital TV
- Video graphics cards
- Digital Video Interface (DVI)
- Notebook Computers
- PCI Express and Serial SATA Ports

### Marking information



Details marking code reference specification of approval list

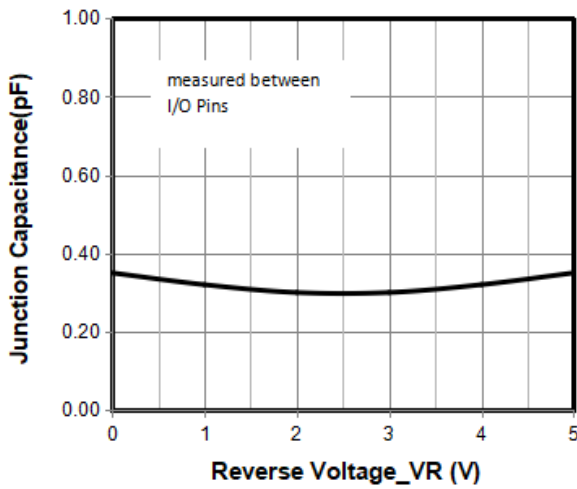
**Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)**

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 $\mu\text{s}$ )	Ppk	80	W
Peak Pulse Current (8/20 $\mu\text{s}$ )	I <sub>PP</sub>	5	A
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	$\pm 25$	kV
ESD per IEC 61000-4-2 (Contact)		$\pm 20$	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	$^{\circ}\text{C}$

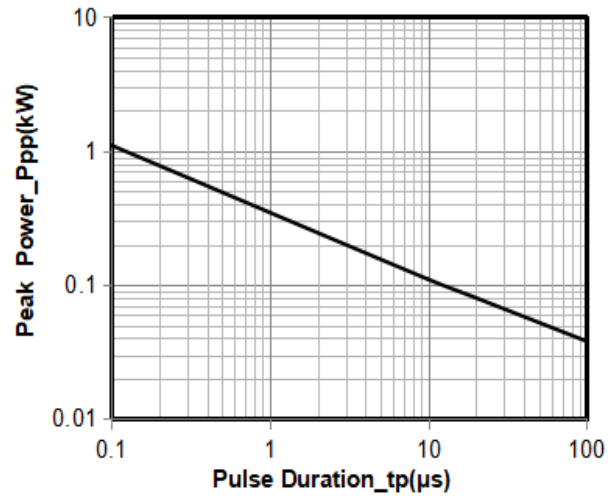
**Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)**

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V <sub>RWM</sub>			5	V	Any I/O pin to ground
Breakdown Voltage	V <sub>BR</sub>	6			V	I <sub>T</sub> = 1mA, any I/O pin to ground
Reverse Leakage Current	I <sub>R</sub>		0.01	0.5	$\mu\text{A}$	V <sub>RWM</sub> = 5V, any I/O pin to ground
Clamping Voltage	V <sub>C</sub>			9	V	I <sub>PP</sub> = 1A (8 x 20 $\mu\text{s}$ pulse), any I/O pin to ground
Clamping Voltage	V <sub>C</sub>			16	V	I <sub>PP</sub> = 5A (8 x 20 $\mu\text{s}$ pulse), any I/O pin to ground
Junction Capacitance	C <sub>J</sub>		0.3	0.4	pF	V <sub>R</sub> = 0V, f = 1MHz, between I/O pins
Junction Capacitance	C <sub>J</sub>			0.8	pF	V <sub>R</sub> = 0V, f = 1MHz, any I/O pin to ground

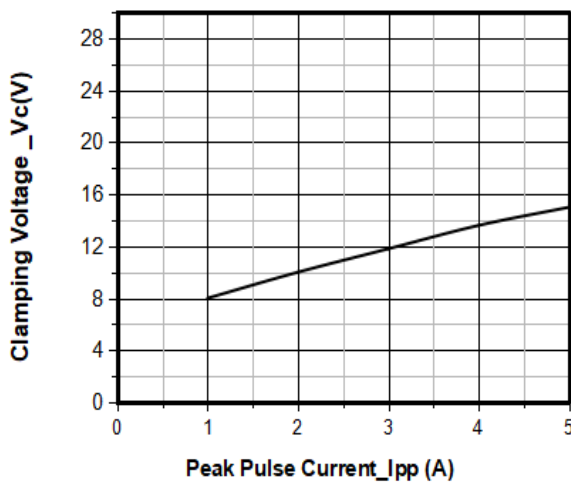
**Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise Specified)**



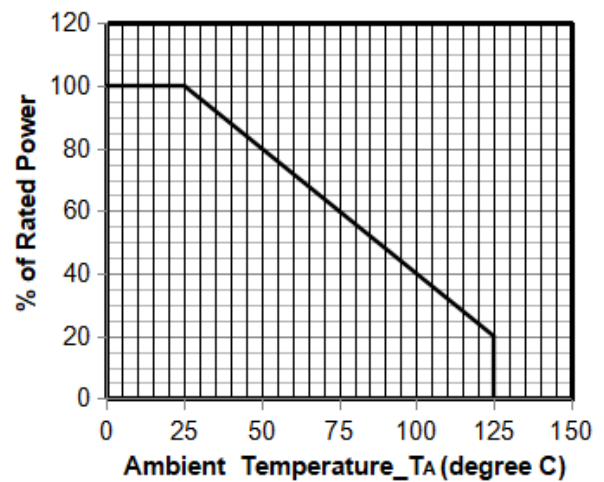
**Junction Capacitance vs. Reverse Voltage**



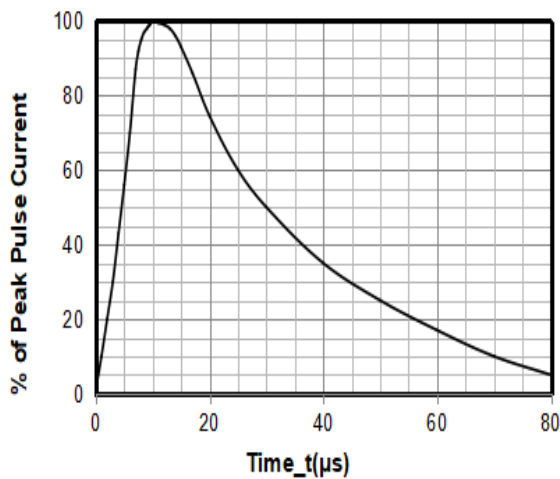
**Peak Pulse Power vs. Pulse Time**



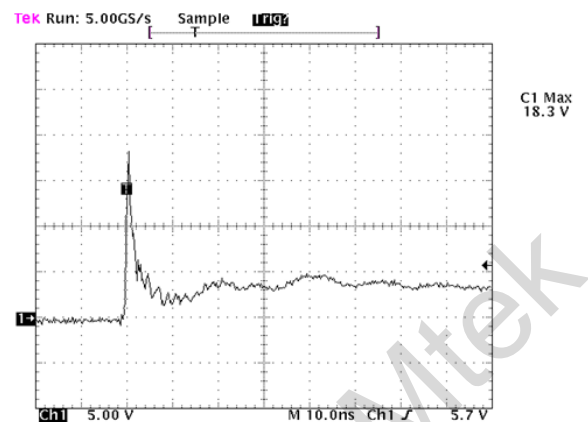
**Clamping Voltage vs. Peak Pulse Current**



**Power Derating Curve**



**8 X 20μs Pulse Waveform**



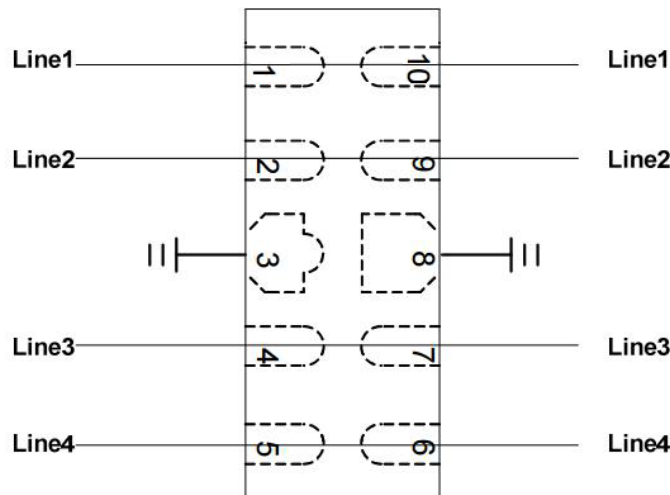
Note: Data is taken with a 10x attenuator

**ESD Clamping Voltage**

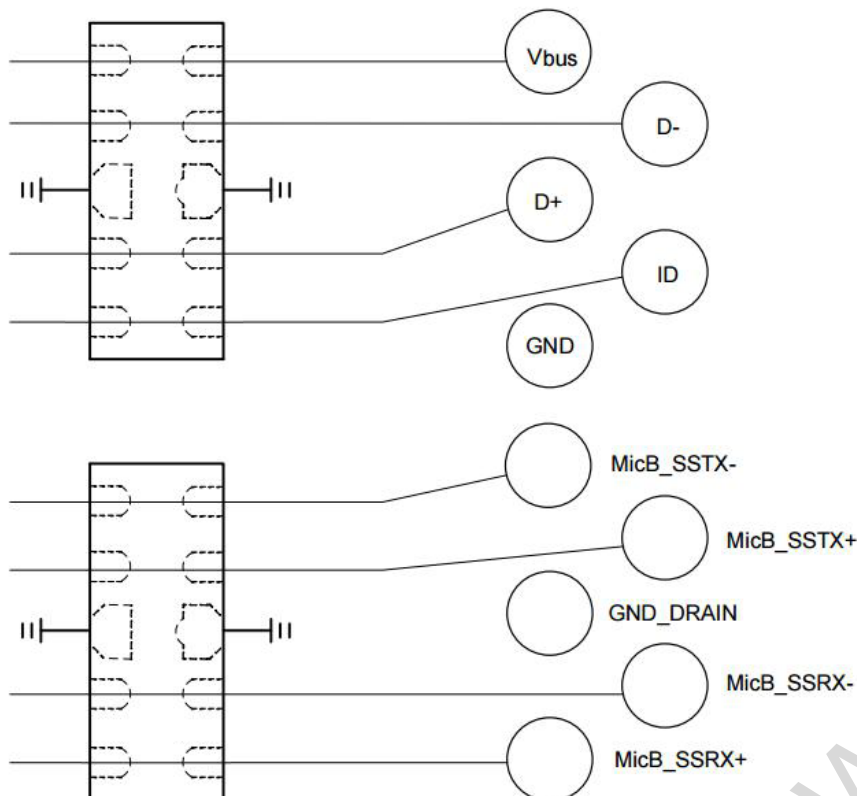
**8 kV Contact per IEC61000-4-2**

## Typical Application

The CLMAP0524P is designed for easy PCB layout by allowing the traces to run straight through the device. The PCB traces could be used to connect the pin pairs for each line. For example, line 1 enters at pin 1 and exits at pin 10 and the PCB trace connects Pin 1 and Pin 10 together. Ground is connected at Pin 3 and Pin 8.

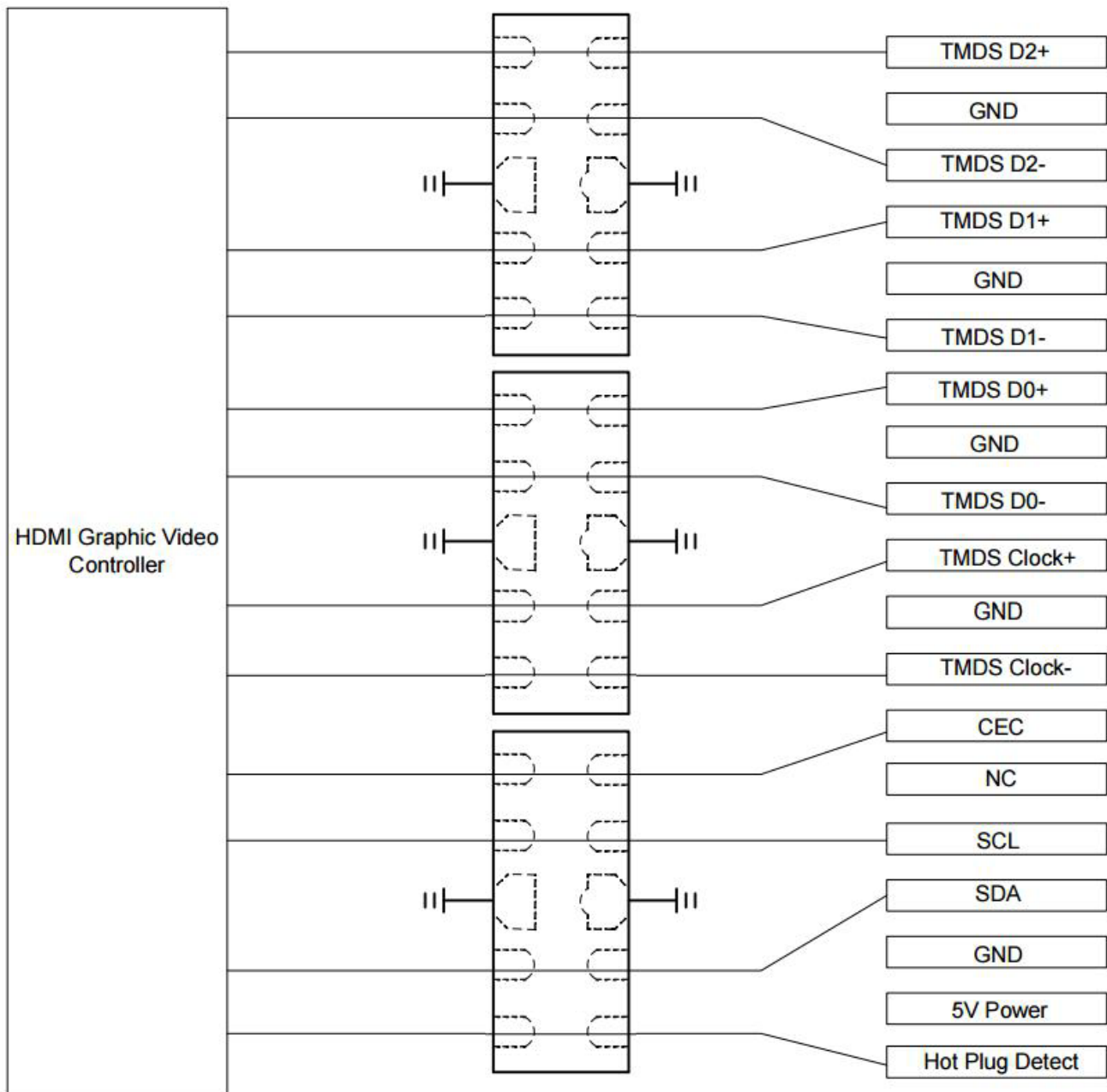


## CLMAP0524P\_SC on USB 3.0 Port Application

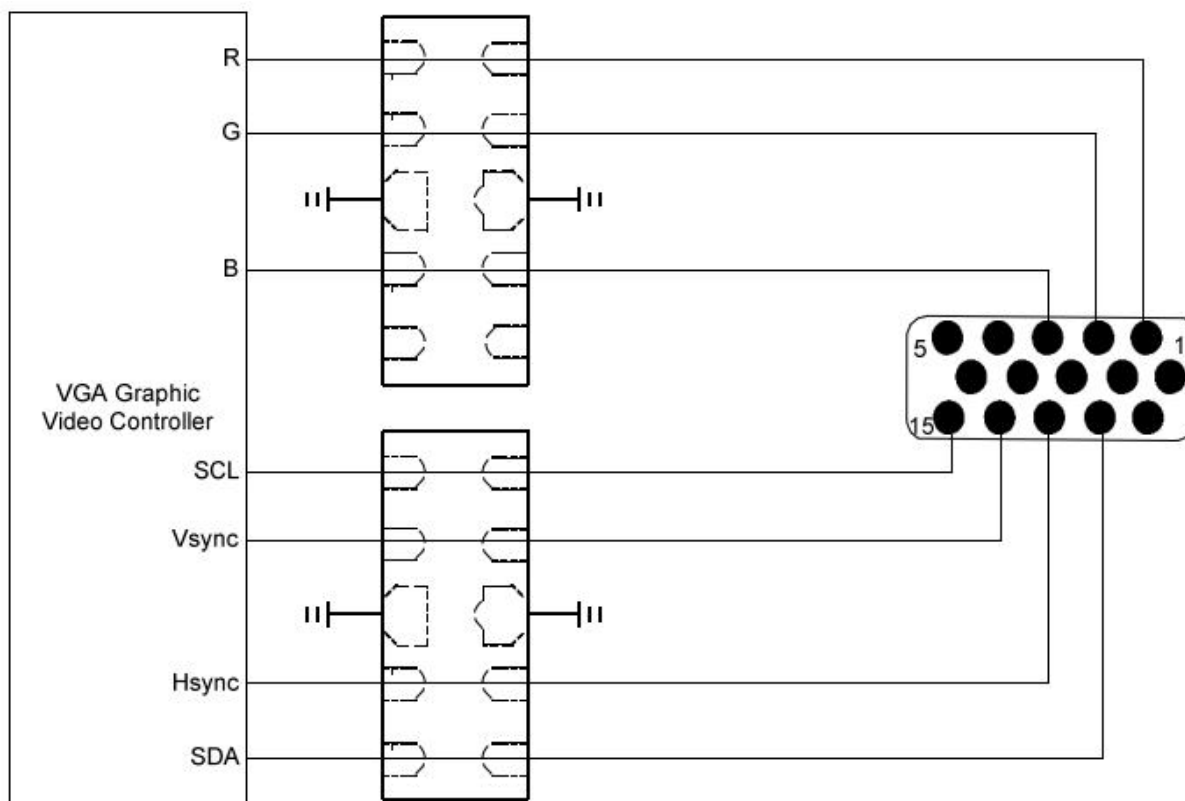


The diagram illustrates the pin connections for a DVI Graphic Video Controller. On the left, a DVI connector is shown with the following signals: Data 2-, Data 2+, Data 4-, Data 4+, DDC Clock, DDC Data, Data 1-, Data 1+, Data 3-, Data 3+, Data 0-, Data 0+, Data 5-, Data 5+, Clock+, Clock-, Red, Green, Blue, and Hsync. On the right, a 25-pin connector is shown with pins numbered 1 through 24 and labeled C1, C2, C3, C4, and C5. The connections are as follows: Data 2- to pin 1, Data 2+ to pin 2, Data 4- to pin 3, Data 4+ to pin 4, DDC Clock to pin 5, DDC Data to pin 6, Data 1- to pin 7, Data 1+ to pin 8, Data 3- to pin 9, Data 3+ to pin 10, Data 0- to pin 11, Data 0+ to pin 12, Data 5- to pin 13, Data 5+ to pin 14, Clock+ to pin 15, Clock- to pin 16, Red to pin 17, Green to pin 18, Blue to pin 19, and Hsync to pin 20. Pins 21 through 24 are labeled C1, C2, C3, and C4 respectively. Pin 25 is labeled C5.

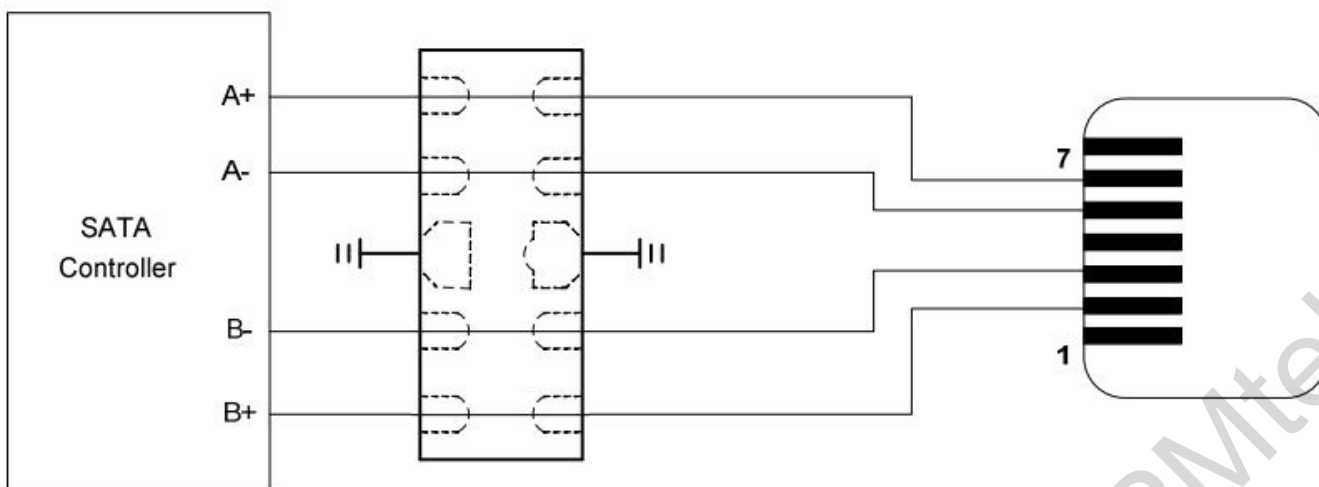
## CLMAP0524P on HDMI Port Application



### CLMAP0524P on VGA Port Application

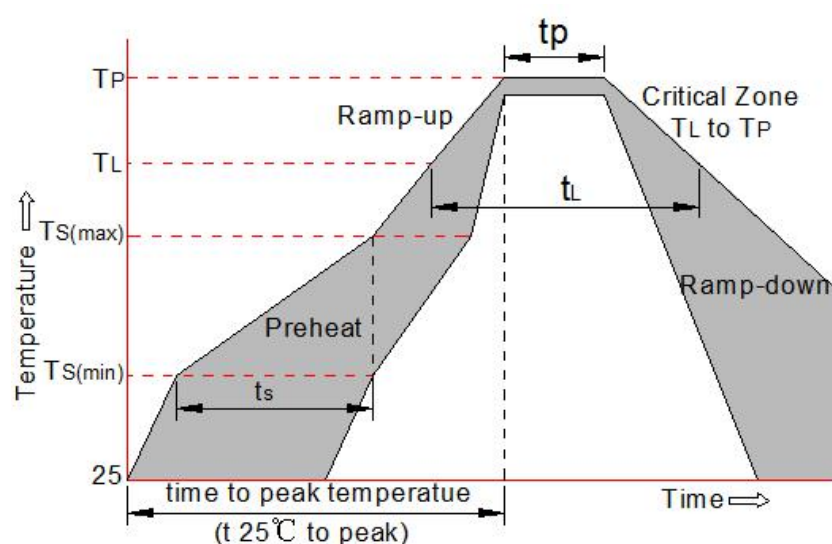


### CLMAP0524P\_SC on SATA Port Application



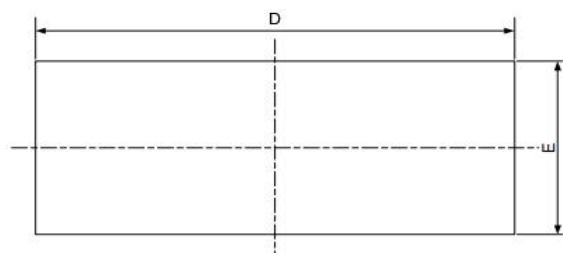
## Soldering parameters

Reflow Condition		Pb-Free assembly (see FIG.2)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C

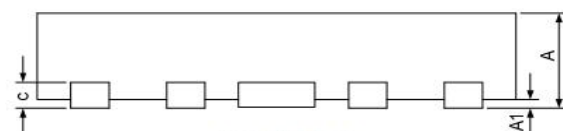




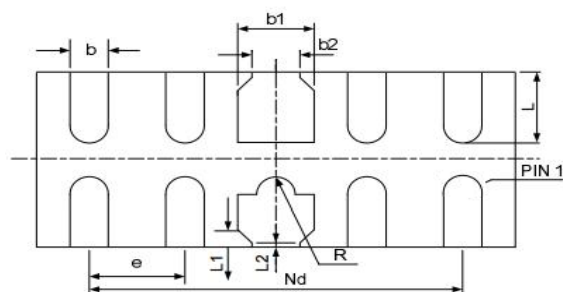
## Package mechanical data



TOP VIEW



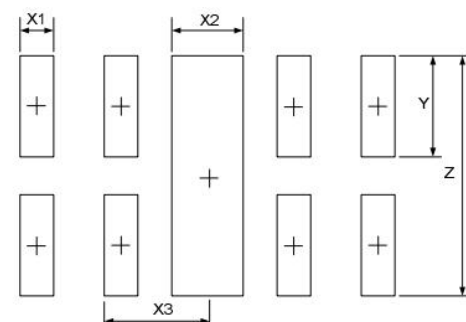
SIDE VIEW



BOTTOM VIEW

SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
b2	0.20	0.25	0.30	0.008	0.010	0.012
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.45	2.50	2.55	0.098	0.100	0.102
e	0.50BSC			0.020BSC		
Nd	2.00BSC			0.080BSC		
E	0.95	1.00	1.05	0.038	0.040	0.042
L	0.35	0.40	0.45	0.014	0.016	0.018
L1	0.075REF			0.003REF		
L2	0.050REF			0.002REF		
h	0.08	0.12	0.15	0.003	0.005	0.006
R	0.05	0.10	0.15	0.002	0.004	0.006

## Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X1	0.200	0.008
X2	0.400	0.016
X3	0.500	0.020
Y	0.600	0.024
Z	1.400	0.056